

Revision History 64K X 16 BIT LOW POWER CMOS SRAM With Error-Correcting Code (ECC)

Revision	Details	Date
Rev 1.0	Initial Release	June. 2022



FEATURES

- Fast access time : 45ns
- Low power consumption: Operating current : 12mA (TYP.)
 Standby current : 1μA (TYP.)
- Single 2.7V ~ 3.6V power supply
- ECC : 1-bit error correction per byte
- All inputs and outputs TTL compatible
- Fully static operation
- Tri-state output
- Data byte control : LB# (DQ0 ~ DQ7) UB# (DQ8 ~ DQ15)
- Data retention voltage : 1.5V (MIN.)
- Package : 44-pin 400mil TSOP II

GENERAL DESCRIPTION

The AS6CE1016A is a 1,048,576-bit low power CMOS static random access memory organized as 65,536 words by 16 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

The AS6CE1016A embeds error-correcting code (ECC) which can correct single-bit error per byte. It is well designed for low power application, and particularly well suited for battery back-up nonvolatile memory application.

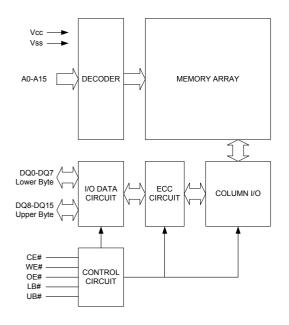
The AS6CE1016A operates from a single power supply of $2.7V \sim 3.6V$ and all inputs and outputs are fully TTL compatible.

PRODUCT FAMILY

Product	Operating		Speed	Power Dissipation		
Family	Temperature	V_{CC} Range	Speed	Standby(I _{SB1} ,TYP.)	Operating(I _{CC} , TYP.)	
AS6CE1016A	-40 ~ 85° ℃	2.7 ~ 3.6V	45ns	1µA	12mA	



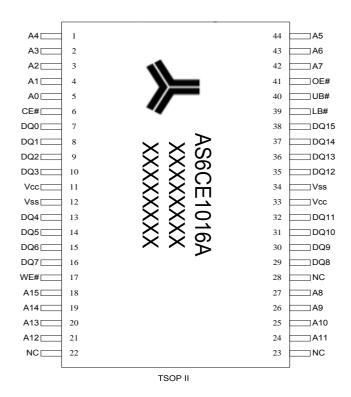
FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0 - A15	Address Inputs
DQ0 – DQ15	Data Inputs/Outputs
CE#	Chip Enable Input
WE#	Write Enable Input
OE#	Output Enable Input
LB#	Lower Byte Control
UB#	Upper Byte Control
V _{CC}	Power Supply
V _{SS}	Ground

PIN CONFIGURATION





ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Voltage on V_{CC} relative to V_{SS}	V _{T1}	-0.5 to 4.6	V
Voltage on any other pin relative to V_{SS}	V _{T2}	-0.5 to V _{CC} +0.5	V
Operating Temperature	T _A	-40 to 85	°C
Storage Temperature	T _{STG}	-65 to 150	°C
Power Dissipation	PD	1	W
DC Output Current	I _{OUT}	50	mA

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

TRUTH TABLE

MODE	CE#	OE#	WE#	LB#	UB#	I/O OPE	RATION	SUPPLY CURRENT
WICDL	02#	OL#	₩₩∟#	LD#	0.0#	DQ0-DQ7	DQ8-DQ15	SUFFEI CORRENT
Standby	H X	X X	X X	X H	X H	High – Z High – Z	High – Z High – Z	I _{SB1}
Output Disable	L	H H	H H	L X	X L	High – Z High – Z	High – Z High – Z	Icc,Icc1
Read	L L L	L L L	H H H	L H L	H L L	D _{OUT} High – Z D _{OUT}	High – Z D _{OUT} D _{OUT}	I _{CC} ,I _{CC1}
Write	L L L	X X X		L H L	ΗLL	D _{IN} High – Z D _{IN}	High – Z D _{IN} D _{IN}	I _{CC} ,I _{CC1}

Note: $H = V_{IH}$, $L = V_{IL}$, X = Don't care.



DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION		MIN.	TYP. *4	MAX.	UNIT
Supply Voltage	V _{CC}			2.7	3.0	3.6	V
Input High Voltage	V _{IH} *1			2.2	-	V _{CC} +0.3	V
Input Low Voltage	V _{IL} *2			- 0.2	-	0.6	V
Input Leakage Current	ILI	$V_{CC} \ge V_{IN} \ge V_{SS}$		- 1	-	1	μA
Output Leakage Current	I _{LO}	$V_{CC} \ge V_{OUT} \ge V_{SS},$ Output Disabled		- 1	-	1	μA
Output High Voltage	V _{OH}	I _{ОН} = -1mA		2.2	2.7	-	V
Output Low Voltage	V _{OL}	I _{OL} = 2mA		-	-	0.4	V
Average Operating	I _{CC}	Cycle time = Min. CE# \leq 0.2V, I _{I/O} = 0mA Others at 0.2V or V _{CC} -0.2V		-	12	20	mA
Power supply Current	I _{CC1}	Cycle time = 1μ s CE# = 0.2V , I_{VO} = 0mA Other pins at 0.2V or V _{CC} - 0.2V		-	3	5	mA
Standby Power		$CL_{\#} \leq V_{CC} = 0.2 V$	Э°С	-	1	3	μA ^{*5}
Supply Current		Others at 0.2V or V _{CC} - 0.2V		-	1	10	μA

Notes:

1. $V_{\text{IH}}(\text{max}) = V_{\text{CC}} + 3.0V$ for pulse width less than 10ns. 2. $V_{\text{L}}(\text{min}) = V_{\text{SS}} - 3.0V$ for pulse width less than 10ns.

3. Over/Undershoot specifications are characterized, not 100% tested.

4. Typical values are included for reference only and are not guaranteed or tested.

Typical values are measured at V_{CC} = V_{CC}(TYP.) and T_A = 25° C

5. This parameter is measured at V_{CC} = 3.0V

CAPACITANCE (T_A = 25°C, f = 1.0MHz)

PARAMETER	SYMBOL	MIN.	MAX	UNIT
Input Capacitance	C _{IN}	-	6	pF
Input/Output Capacitance	C _{I/O}	-	8	pF

Note : These parameters are guaranteed by device characterization, but not production tested.

AC TEST CONDITIONS

Input Pulse Levels	0.2V to V _{CC} - 0.2V
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	$C_L = 30pF + 1TTL, I_{OH}/I_{OL} = -1mA/2mA$



AC ELECTRICAL CHARACTERISTICS

(1) READ CYCLE

PARAMETER	SYM.	AS6CE1	AS6CE1016A-45		
		MIN.	MAX.		
Read Cycle Time	t _{RC}	45	-	ns	
Address Access Time	t _{AA}	-	45	ns	
Chip Enable Access Time	t _{ACE}	-	45	ns	
Output Enable Access Time	t _{OE}	-	25	ns	
Chip Enable to Output in Low-Z	t _{CLZ} *	10	-	ns	
Output Enable to Output in Low-Z	t _{oLZ} *	5	-	ns	
Chip Disable to Output in High-Z	t _{CHZ} *	-	15	ns	
Output Disable to Output in High-Z	t _{OHZ} *	-	15	ns	
Output Hold from Address Change	t _{он}	10	-	ns	
LB#, UB# Access Time	t _{BA}	-	45	ns	
LB#, UB# to High-Z Output	t _{BHZ} *	-	20	ns	
LB#, UB# to Low-Z Output	t _{BLZ} *	10	-	ns	

(2) WRITE CYCLE

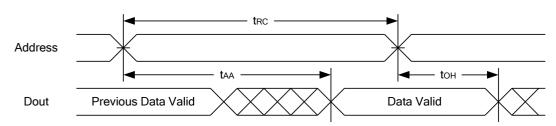
PARAMETER	SYM.	AS6CE1	UNIT	
		MIN.	MAX.	
Write Cycle Time	t _{wc}	45	-	ns
Address Valid to End of Write	t _{AW}	40	-	ns
Chip Enable to End of Write	t _{CW}	40	-	ns
Address Set-up Time	t _{AS}	0	-	ns
Write Pulse Width	t _{WP}	35	-	ns
Write Recovery Time	t _{wR}	0	-	ns
Data to Write Time Overlap	t _{DW}	20	-	ns
Data Hold from End of Write Time	t _{DH}	0	-	ns
Output Active from End of Write	t _{ow} *	5	-	ns
Write to Output in High-Z	t _{wHZ} *	-	15	ns
LB#, UB# Valid to End of Write	t _{BW}	35	-	ns

*These parameters are guaranteed by device characterization, but not production tested.

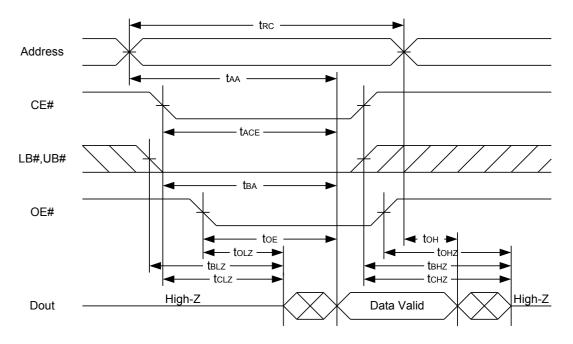


TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2)



READ CYCLE 2 (CE# and OE# Controlled) (1,3,4,5)



Notes :

1.WE# is high for read cycle.

2.Device is continuously selected OE# = low, CE# = low, LB# or UB# = low.

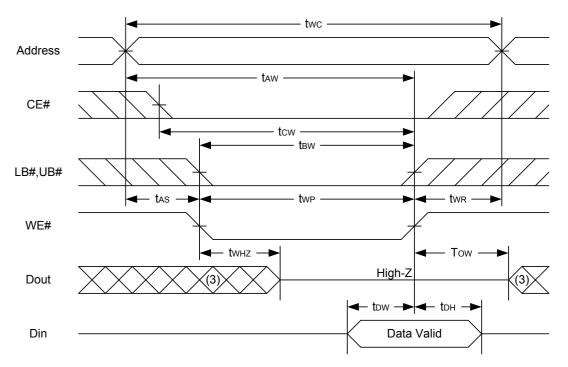
3.Address must be valid prior to or coincident with CE# = low, LB# or UB# = low transition; otherwise t_{AA} is the limiting parameter.

 $4.t_{\text{CLZ}}, t_{\text{BLZ}}, t_{\text{CLZ}}, t_{\text{CHZ}}, t_{\text{BHZ}} \text{ and } t_{\text{OHZ}} \text{ are specified with } C_{\text{L}} = 5 \text{pF}. \text{ Transition is measured } \pm 500 \text{mV} \text{ from steady state.}$

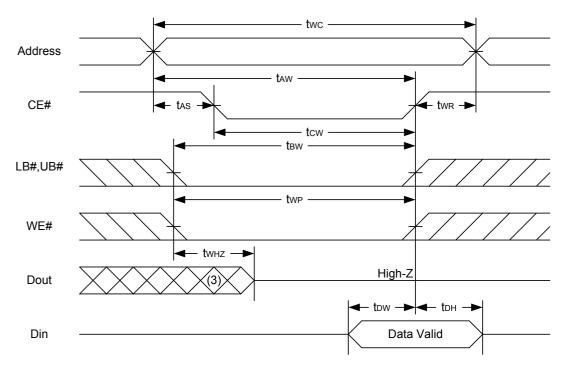
5.At any given temperature and voltage condition, t_{CHZ} is less than t_{CLZ} , t_{BHZ} is less than t_{BLZ} , t_{OHZ} is less than t_{OLZ} .



WRITE CYCLE 1 (WE# Controlled) (1,2,4,5)

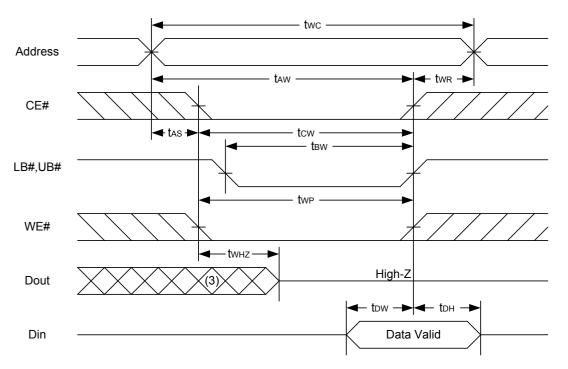


WRITE CYCLE 2 (CE# Controlled) (1,4,5)





WRITE CYCLE 3 (LB#,UB# Controlled) (1,4,5)



Notes :

1.A write occurs during the overlap of a low CE#, low WE#, LB# or UB# = low.

2.During a WE# controlled write cycle with OE# low, t_{WP} must be greater than $t_{WHZ} + t_{DW}$ to allow the drivers to turn off and data to be placed on the bus.

3. During this period, I/O pins are in the output state, and input signals must not be applied.

4.If the CE#, LB#, UB# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.

 $5.t_{OW}$ and t_{WHZ} are specified with C_L = 5pF. Transition is measured ±500mV from steady state.



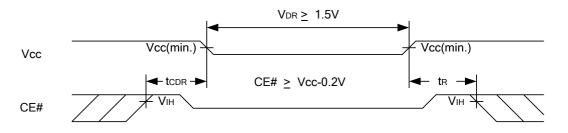
DATA RETENTION CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
V _{CC} for Data Retention	V _{DR}	$CE\# \geq V_{CC} - 0.2V$		1.5	-	3.6	V
Data Retention Current		$V_{cc} = 1.5V$	40 ℃	-	1	3	μA
Data Retention Current	I _{DR}	CE# \geq V _{CC} - 0.2V Other pins at 0.2V or V _{CC} -0.2V		-	1	10	μA
Chip Disable to Data Retention Time	t	See Data Retention Waveforms (below)		0	-	-	ns
Recovery Time	t _R			t _{RC⁺}	-	-	ns

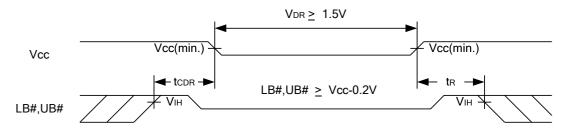
 t_{RC^*} = Read Cycle Time

DATA RETENTION WAVEFORM

Low Vcc Data Retention Waveform (1) (CE# controlled)



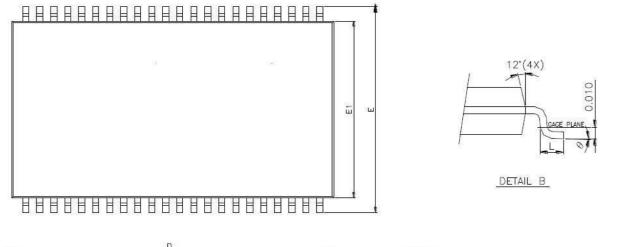
Low Vcc Data Retention Waveform (2) (LB#, UB# controlled)

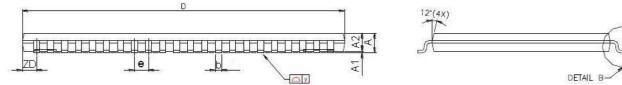




PACKAGE OUTLINE DIMENSION

44-pin 400mil TSOP II Package Outline Dimension





SYMBOLS	DIMENSI	ONS IN MILL	METERS	DIME	DIMENSIONS IN MILS			
STNIBOLS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
A	-	-	1.20	-	-	47.2		
A1	0.05	0.10	0.15	2.0	3.9	5.9		
A2	0.95	1.00	1.05	37.4	39.4	41.3		
b	0.30	-	0.45	11.8	-	17.7		
С	0.12	-	0.21	4.7	-	8.3		
D	18.212	18.415	18.618	717	725	733		
E	11.506	11.760	12.014	453	463	473		
E1	9.957	10.160	10.363	392	400	408		
е	-	0.800	-	-	31.5	-		
L	0.40	0.50	0.60	15.7	19.7	23.6		
ZD	-	0.805	-	-	31.7	-		
У	-	-	0.076	-	-	3		
θ	0°	3°	6°	0°	3°	6°		



ORDERING INFORMATION

Alliance Part Number	Organization	VCC Range	Package	Operating Temp	Speed ns
AS6CE1016A-45ZIN	64K x 16	2.7 ~ 3.6V	44-pin 400 mil TSOP II	Industrial -40°C ~ 85°C	45

PART NUMBERING SYSTEM

AS6C	E1016A	-45	z	I	N	хх
AS6C = Low Power SRAM	Device Number E=With ECC 10 = 1Meg 16 = x 16 bit A = A die version	Access Time 45 = 45ns	Z =TSOPII	I = Industrial Temp -40°C~ 85°C	Indicates Pb and Halogen Free	Packing Type None : Tray TR : Reel





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